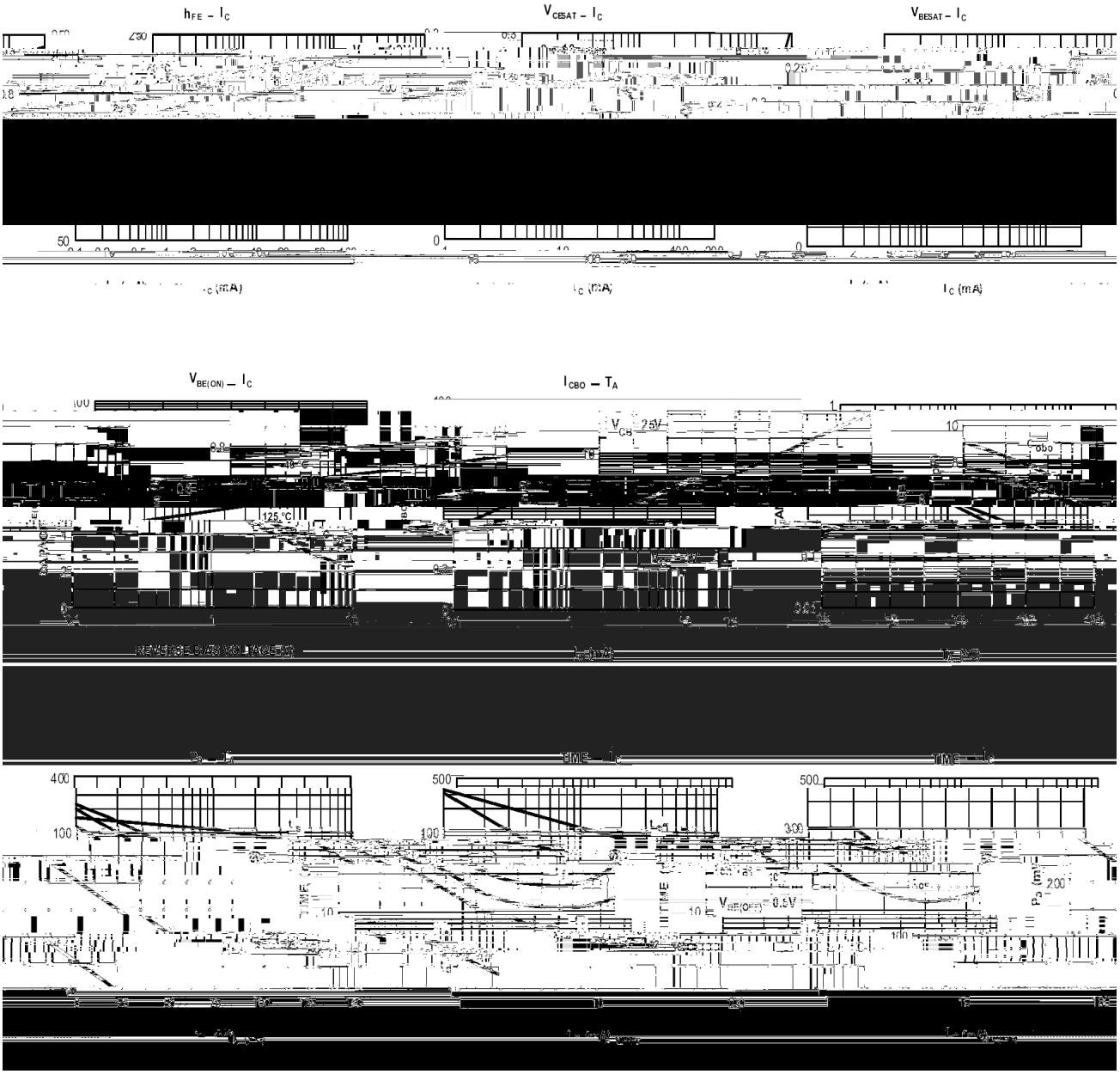
# MMBT3906

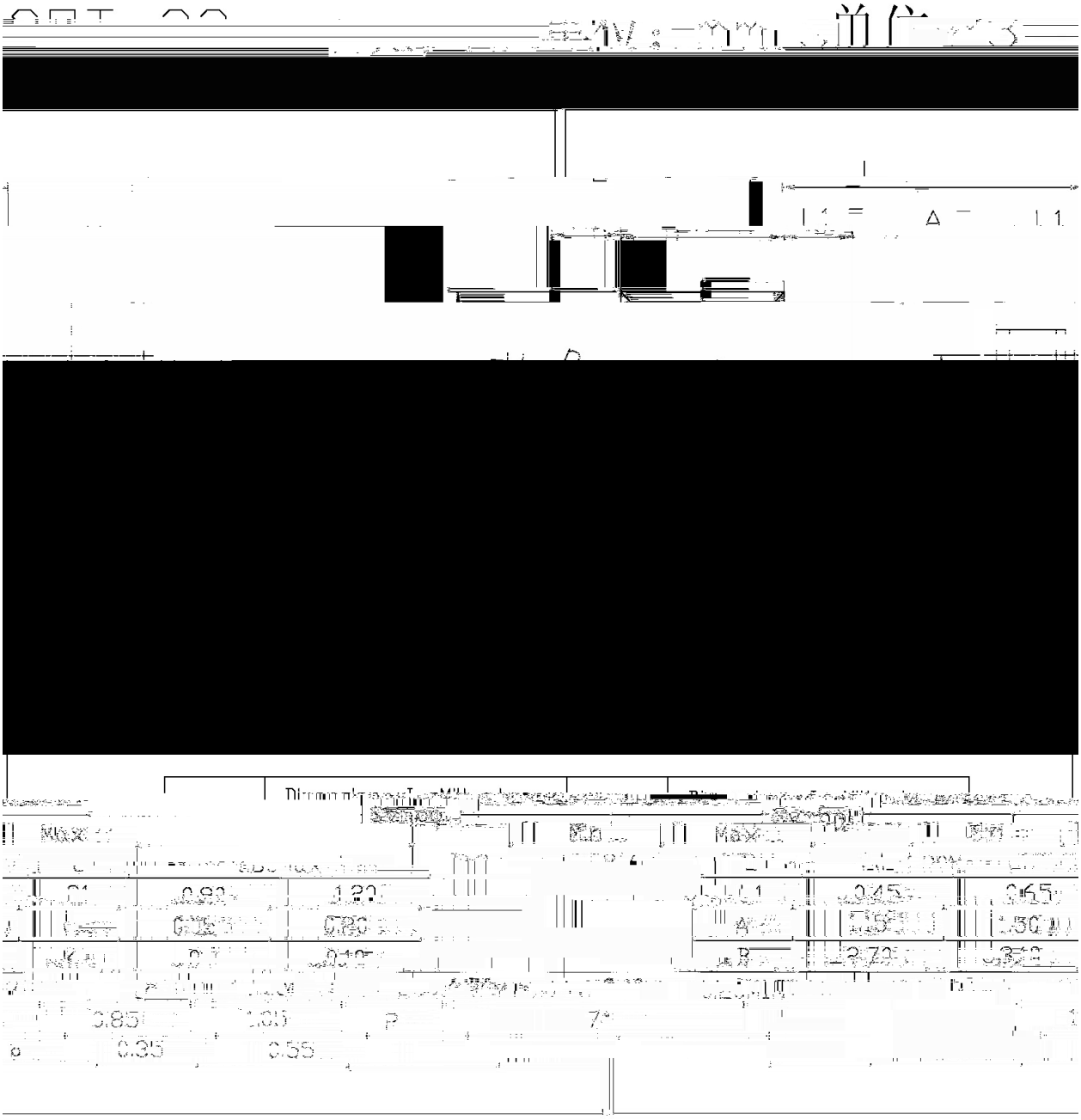
| Parameter | Symbol | Rating | Unit |
|---|---|---|---|
| Collector to Base Voltage | $V_{CBO}$ | -40 | V |
| Collector to Emitter Voltage | $V_{CEO}$ | -40 | V |
| Emitter to Base Voltage | $V_{EBO}$ | -5.0 | V |
| Collector Current | $I_C$ | -200 | mA |
| Collector Power Dissipation | $P_C$ | 300 | mW |
| Junction Temperature | $T_j$ | 150 | ℃ |
| Storage Temperature Range | $T_{stg}$ | -55～150 | ℃ |

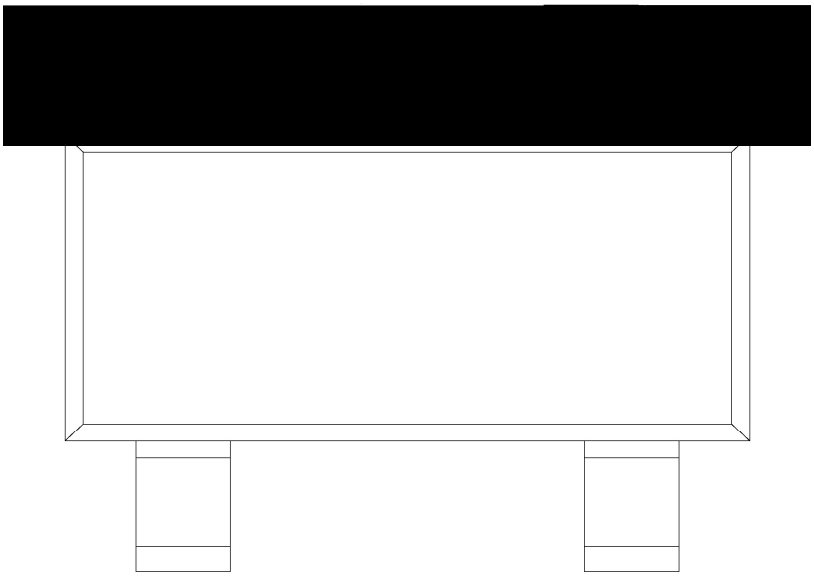
| Parameter | Symbol | Test Conditions | Min | T |
|---|---|---|---|---|

## / Electrical Characteristic Curve

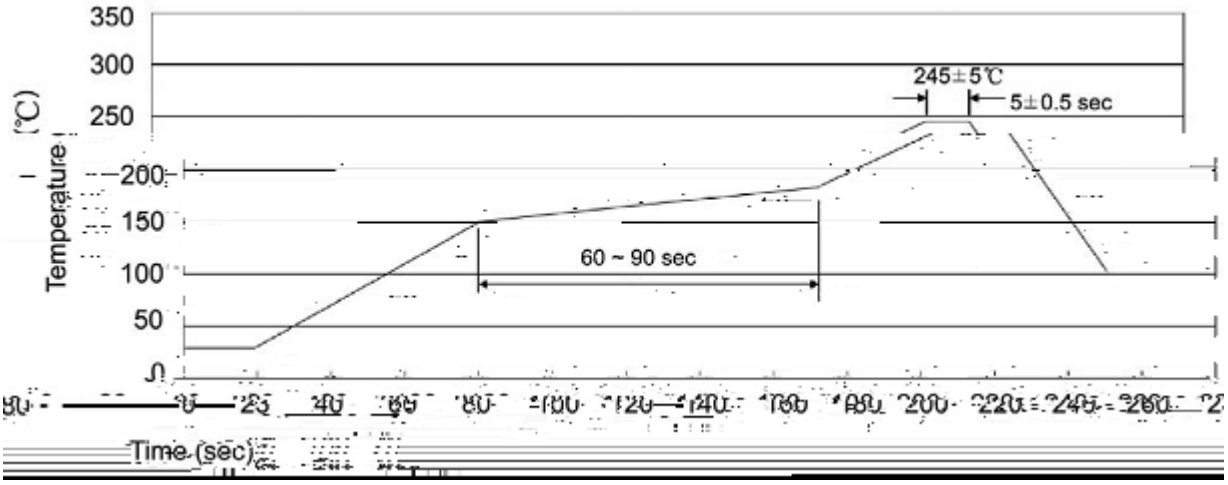


## / Package Dimensions





## ( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)




Note:

1 25 150 60 90sec;

1.Preheating:25~150 , Time:60~90sec.

2 245±5 5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3 2 10 /sec.

3. Cooling Speed: 2~10 /sec.

## / Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5℃ Time:10±1 sec

## / Packaging SPEC.

/ REEL

| Package Type ! | Units " # $ | Dimension " % & (unit ' $mm^3$) |
|---|---|---|